REMARKS/ARGUMENTS

The Applicant thanks the Examiner for the Official Action dated June 3, 2004. In response to the issues raised, we offer the following submissions.

Amendments

Claim 1 has been amended to clarify that the printhead is not a claimed integer, but the core must have an area that is capable of having the printhead bonded to it.

Statutory Double Patenting

Claims 1 to 19 stand rejected as having the same scope as claims 1 to 20 of our co-pending application USSN 10/713,067. The Applicant disagrees. All the claims of the present and co-pending applications define different combinations of features. These different combinations of claimed features give each claim an individual scope, none being co-extensive with another.

Firstly, the claims of the present application are limited to a core for a printhead assembly that is capable of receiving a printhead in a specific area by bonding. In contrast, the claims of '067 are directed to a printhead assembly with a core having a printhead bonded to it. Hence the printhead is not a claimed feature. This in itself differentiates the scopes of the present application from those of '067. An elongate core for a printhead assembly without a printhead bonded to it may infringe claim 1 of the present application, but would not directly infringe the claims of '067. Obviously, if a product can infringe one set of claims but not another, the claim sets are of differing scopes.

The claims have other features and limitations which do not appear in the '067 claims specified by the Examiner. A selection of these differences have been highlighted in the response to the Examiner's report dated June 10, 2004 on '067. For the Examiner's convenience, these are set out below.

'067 Claim 1.
"... **MEMS** printhead ...", "... outer, **laminated** shell ..."

'067 Claim 2.
"... formed from ***different*** metals ..."

'067 Claim 3.
Includes non-modular printheads.

'067 Claim 4.
Includes layers of the same materials.

'067 Claim 5.
Both shell and core may have coefficients of thermal expansion (CTE) greater, or less than, the CTE of silicon.

From the above, it is clear that the claims of the present application are not co-extensive with the claims of USSN 10/713,067.

The Applicant respectfully submits that the claims rejection has been successfully traversed. Accordingly favorable reconsideration and allowance of the application is courteously solicited.

Very respectfully,

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